



Material Content Data Sheet



Sales Product Name		IPD100N06S4-03		Issued		27. September 2017		
MA#		MA000755362						
Package		PG-TO252-3-11		Weight*		377.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.184	1.37	1.37	13724	13724
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		570	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		171	
	non noble metal	copper	7440-50-8	215.017	56.92	57.00	569252	569993
wire	non noble metal	aluminium	7429-90-5	50.070	13.26	13.26	132559	132559
encapsulation	organic material	carbon black	1333-86-4	0.802	0.21		2122	
	plastics	epoxy resin	-	14.028	3.71		37139	
	inorganic material	silicondioxide	60676-86-0	65.330	17.30	21.22	172960	212221
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9902	9902
plating	non noble metal	nickel	7440-02-0	0.091	0.02		240	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	241
solder	noble metal	silver	7440-22-4	0.099	0.03		263	
	non noble metal	tin	7440-31-5	0.079	0.02		210	
	non noble metal	lead	7439-92-1	3.796	1.00	1.05	10049	10522
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	copper	7440-50-8	19.177	5.08	5.09	50772	50838
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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